NOTES: (UNLESS OTHERWISE SPECIFIED)

1. BOARD FABRICATION METHODS MUST COMPLY WITH:
   QORVO PCB FABRICATION SPECIFICATIONS PCB-21-1001.
   A COPY OF PCB-21-1001 CAN BE OBTAINED FROM QORVO UPON REQUEST.
   FABRICATE IN ACCORDANCE WITH IPC-6018B, per IPC-6011, CLASS 2.

2. ARTWORK FORMAT:
   GERBER 274X*
   *GERBER DATA SUPPLIED WITH DESIRED FINAL TRACE WIDTHS. PROCESS
   COMPENSATION TRACE WIDTH ADJUSTMENTS TO BE DONE BY PCB FABRICATOR.

3. MATERIAL:
   NUMBER OF LAYERS: 4 LAYERS
   METAL 1: 0.5oz.
   CORE 1: ROGERS 4003C, 0.008in. THICK
   METAL 2: 0.5oz.
   PREPREG: EPOXY COATED GLASS FABRIC
   METAL 3: 0.5oz.
   CORE 1: 370HR, .006 THICK
   METAL 4: 0.5oz.

   SOLDERMASK TOP: LPI (LIQUID PHOTO-IMAGEABLE),
   OR LDI(LASED DIRECT IMAGEABLE), GREEN
   MAX FINISH THICKNESS OF SOLDERMASK TO BE 0.001in.
   SILKSCREEN TOP: HIGH TEMPERATURE, NON-CONDUCTIVE, WHITE EPOXY BASED INK.

4. FINISH PLATING:
   METAL 1 AND METAL 4:
   ENIG (ELECTROLESS NICKEL/IMMERSION GOLD):

5. FINISHED BOARD THICKNESS: 0.025 ±0.003in.

6. COPPER IS PULLED BACK 0.002in. FROM EDGE OF BOARD ON METAL 1 AND METAL 4.
   AND PULLED BACK 0.003-0.005in. FROM EDGE OF BOARD ON INTERNAL LAYERS.
   THESE VALUES ARE CRITICAL AND MUST BE INSPECTED.

7. TOLERANCE: PC BOARD OUTLINE: ±0.002in.

8. BURRS SHALL NOT EXCEED 0.002in.

9. VIA PLATING/FILLING:
   A. ALL VIAS UNDER THE DUT ARE TO BE COPPER-FILLED, OVER-PLATED AND PLANARIZED.
      FINISHED COPPER THICKNESS TO BE 0.0014 ±0.0004in.
   B. ALL OTHER PLATED THRU HOLES TO BE PLATED TO 0.0007in. MIN. THICKNESS.

10. METAL 1(TOP) AND METAL2(BOTTOM) AFTER OVERPLATING AND PLANARIZATION SHALL HAVE A MAX
    ALLOWABLE NEGATIVE FEATURE OF 0.0008in. AND A MAX ALLOWABLE POSITIVE FEATURE OF 0.0003in.

11. CONDUCTOR WIDTHS AND SPACING TO BE WITHIN 0.001in. OF CAD DATABASE.

12. SOLDERMASK IN PLATED-THRU HOLES IS ACCEPTABLE AS LONG AS IT DOES NOT EXIST
    ON BACKSIDE OF BOARD.

13. ALL HOLES TO BE LOCATED WITHIN ±0.003 OF CAD DATABASE.

14. NO VENDOR MARKING OR SERIALIZATION ALLOWED.

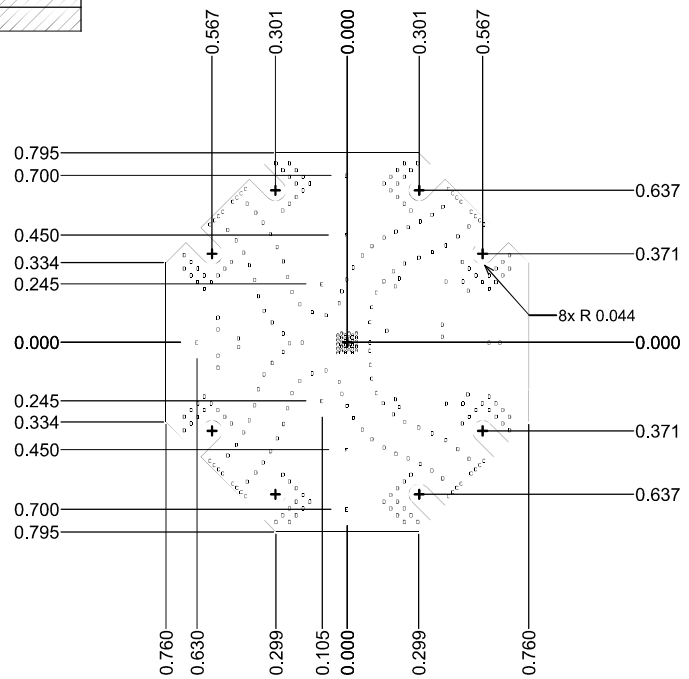
15. BOARDS SHALL BE SINGULATED AND BAGGED

16. NO ELECTRICAL TEST

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	SILKSCREEN_TOP				
2	SOLDERMASK_TOP	Solder Resist	0.10mil	4.3	
3	METAL1_TOP	Copper	0.70mil		
4	DIELECTRIC 1	ROGERS 4003C	8.00mil	3.38	
5	METAL2_MID1	Copper	0.70mil		
6	DIELECTRIC 2	370HR	6.00mil	4.04	
7	METAL3_MID2	Copper	0.70mil		
8	DIELECTRIC 3	370HR	6.00mil	4.04	
9	METAL4_BOT	Copper	0.70mil		

REVISION HISTORY

REV	DESCRIPTION	DATE	APPROVAL
A	New Release	06/23/16	OMARRUFO



Symbol	Count	Hole Size	Hole Finish/Drill	Plated	Hole Type	Drill Layer Pair	Filled
A	30	8.00mil (0.203mm)	Drill	PTH	Round	METAL1_TOP - METAL4_BOT	YES
B	14	10.00mil (0.254mm)	Drill	PTH	Round	METAL1_TOP - METAL3_MID2	
C	40	15.00mil (0.381mm)	Drill	PTH	Round	METAL1_TOP - METAL4_BOT	
D	199	20.00mil (0.508mm)	Drill	PTH	Round	METAL1_TOP - METAL4_BOT	
E	5	100.00mil (2.540mm)	Drill	PTH	Round	METAL1_TOP - METAL4_BOT	
F	2	120.00mil (3.048mm)	Drill	PTH	Round	METAL1_TOP - METAL4_BOT	

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UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN INCHES [mm]

TOLERANCES
.XX = ±.01
.XXX = ±.005
.XXXX = ±.0010
ANGLES = ±0.5°

INTERPRET DRAWING PER ANSI/ASME Y14.5 - 2009

THIRD ANGLE PROJECTION

DO NOT SCALE DRAWING

SAP NO. 281519

APPROVAL AND RELEASE RECORDS MAINTAINED IN PDE

		DATE
DESIGNER	OMARRUFO	8/3/2016
ENGR.	TNGUYEN	8/3/2016

PDE CONTROLLED

CAGE CODE 1CVM1

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TITLE: PCB, QPC1006

SIZE B | DWG. NO. QPC1006-4000 | REV. A

SCALE: NTS | SHEET 1 OF 4